

$$V_{CES} = 1200V$$

$$I_C = 65A, T_C = 100^{\circ}C$$

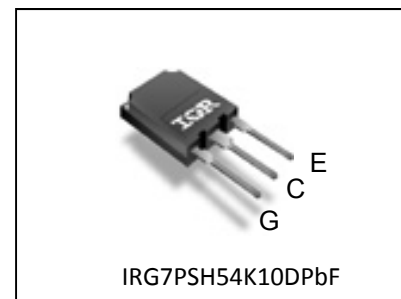
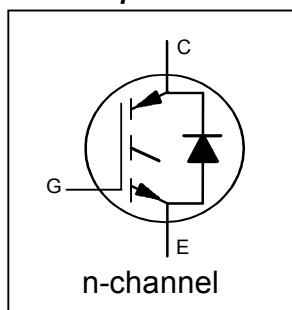
$$t_{SC} \geq 10\mu s, T_{J(max)} = 150^{\circ}C$$

$$V_{CE(ON)} \text{ typ.} = 1.9V @ I_C = 50A$$

### Applications

- Industrial Motor Drive
- UPS
- Solar Inverters
- Welding

### Insulated Gate Bipolar Transistor with Ultrafast Soft Recovery Diode



|      |           |         |
|------|-----------|---------|
| G    | C         | E       |
| Gate | Collector | Emitter |

| Features                                      | Benefits                                        |
|-----------------------------------------------|-------------------------------------------------|
| Low $V_{CE(ON)}$ and switching losses         | High efficiency in a Wide Range of Applications |
| 10 $\mu s$ Short Circuit SOA                  | Rugged Transient Performance                    |
| Square RBSOA                                  | Increased Reliability                           |
| Maximum Junction Temperature 150 $^{\circ}C$  | Excellent Current Sharing in Parallel Operation |
| Positive $V_{CE(ON)}$ Temperature Coefficient |                                                 |

| Base part number | Package Type | Standard Pack |          | Orderable Part Number |
|------------------|--------------|---------------|----------|-----------------------|
|                  |              | Form          | Quantity |                       |
| IRG7PSH54K10DPbF | Super-247    | Tube          | 25       | IRG7PSH54K10DPbF      |

### Absolute Maximum Ratings

|                            | Parameter                                           | Max.                              | Units |
|----------------------------|-----------------------------------------------------|-----------------------------------|-------|
| $V_{CES}$                  | Collector-to-Emitter Voltage                        | 1200                              | V     |
| $I_C @ T_C = 25^{\circ}C$  | Continuous Collector Current                        | 120                               | A     |
| $I_C @ T_C = 100^{\circ}C$ | Continuous Collector Current                        | 65                                |       |
| $I_{CM}$                   | Pulse Collector Current, $V_{GE}=20V$               | 200                               |       |
| $I_{LM}$                   | Clamped Inductive Load Current, $V_{GE}=20V$ ①      | 200                               |       |
| $I_F @ T_C = 25^{\circ}C$  | Diode Continuous Forward Current                    | 50                                |       |
| $I_F @ T_C = 100^{\circ}C$ | Diode Continuous Forward Current                    | 25                                | V     |
| $V_{GE}$                   | Continuous Gate-to-Emitter Voltage                  | $\pm 30$                          |       |
| $P_D @ T_C = 25^{\circ}C$  | Maximum Power Dissipation                           | 520                               | W     |
| $P_D @ T_C = 100^{\circ}C$ | Maximum Power Dissipation                           | 210                               |       |
| $T_J$<br>$T_{STG}$         | Operating Junction and<br>Storage Temperature Range | -40 to +150                       | C     |
|                            | Soldering Temperature, for 10 sec.                  | 300 (0.063 in. (1.6mm) from case) |       |
|                            | Mounting Torque, 6-32 or M3 Screw                   | 10 lbf-in (1.1 N·m)               |       |

### Thermal Resistance

|                         | Parameter                                                      | Min. | Typ. | Max. | Units         |
|-------------------------|----------------------------------------------------------------|------|------|------|---------------|
| $R_{\theta JC}$ (IGBT)  | Thermal Resistance Junction-to-Case-(each IGBT) ②              | —    | —    | 0.24 | $^{\circ}C/W$ |
| $R_{\theta JC}$ (Diode) | Thermal Resistance Junction-to-Case-(each Diode) ②             | —    | —    | 0.70 |               |
| $R_{\theta CS}$         | Thermal Resistance, Case-to-Sink (flat, greased surface)       | —    | 0.24 | —    |               |
| $R_{\theta JA}$         | Thermal Resistance, Junction-to-Ambient (typical socket mount) | —    | —    | 40   |               |

**Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

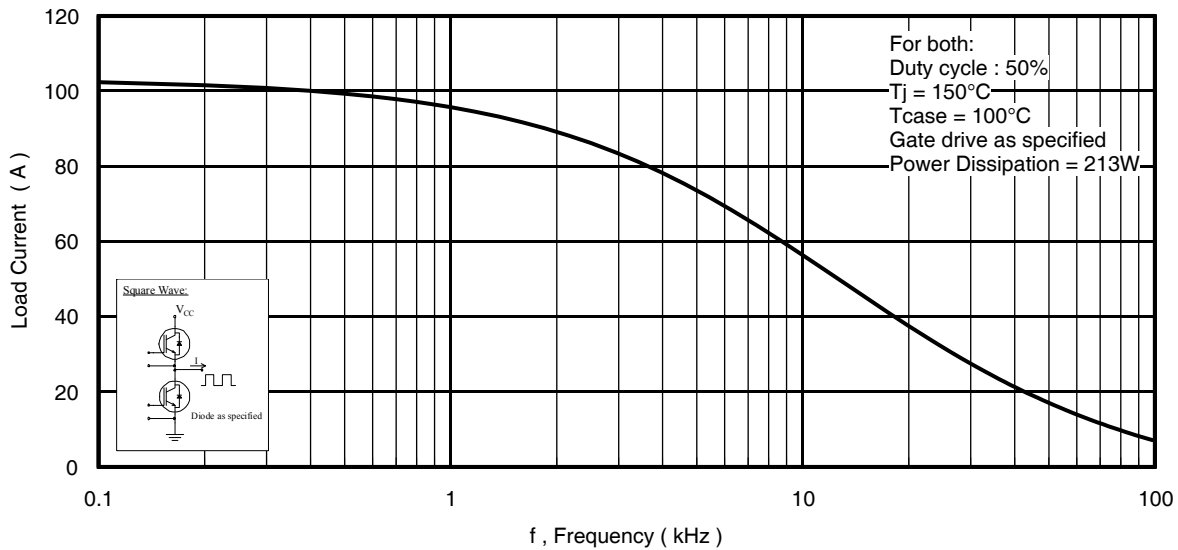
|                                 | Parameter                               | Min. | Typ. | Max.      | Units   | Conditions                                             |
|---------------------------------|-----------------------------------------|------|------|-----------|---------|--------------------------------------------------------|
| $V_{(BR)CES}$                   | Collector-to-Emitter Breakdown Voltage  | 1200 | —    | —         | V       | $V_{GE} = 0V, I_C = 250\mu A$ ③                        |
| $\Delta V_{(BR)CES}/\Delta T_J$ | Temperature Coeff. of Breakdown Voltage | —    | 1.3  | —         | V/°C    | $V_{GE} = 0V, I_C = 5mA$ (25°C-150°C)                  |
| $V_{CE(on)}$                    | Collector-to-Emitter Saturation Voltage | —    | 1.9  | 2.4       | V       | $I_C = 50A, V_{GE} = 15V, T_J = 25^\circ\text{C}$      |
|                                 |                                         | —    | 2.4  | —         |         | $I_C = 50A, V_{GE} = 15V, T_J = 150^\circ\text{C}$     |
| $V_{GE(th)}$                    | Gate Threshold Voltage                  | 5.0  | —    | 7.5       | V       | $V_{CE} = V_{GE}, I_C = 2.4mA$                         |
| $\Delta V_{GE(th)}/\Delta T_J$  | Threshold Voltage Temperature Coeff.    | —    | -15  | —         | mV/°C   | $V_{CE} = V_{GE}, I_C = 2.4mA$ (25°C-150°C)            |
| $g_{fe}$                        | Forward Transconductance                | —    | 36   | —         | S       | $V_{CE} = 50V, I_C = 50A, PW = 20\mu s$                |
| $I_{CES}$                       | Collector-to-Emitter Leakage Current    | —    | 1.0  | 45        | $\mu A$ | $V_{GE} = 0V, V_{CE} = 1200V$                          |
|                                 |                                         | —    | 1800 | —         |         | $V_{GE} = 0V, V_{CE} = 1200V, T_J = 150^\circ\text{C}$ |
| $I_{GES}$                       | Gate-to-Emitter Leakage Current         | —    | —    | $\pm 200$ | nA      | $V_{GE} = \pm 30V$                                     |
| $V_F$                           | Diode Forward Voltage Drop              | —    | 2.5  | 3.5       | V       | $I_F = 16A$                                            |
|                                 |                                         | —    | 2.1  | —         |         | $I_F = 16A, T_J = 150^\circ\text{C}$                   |

**Switching Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

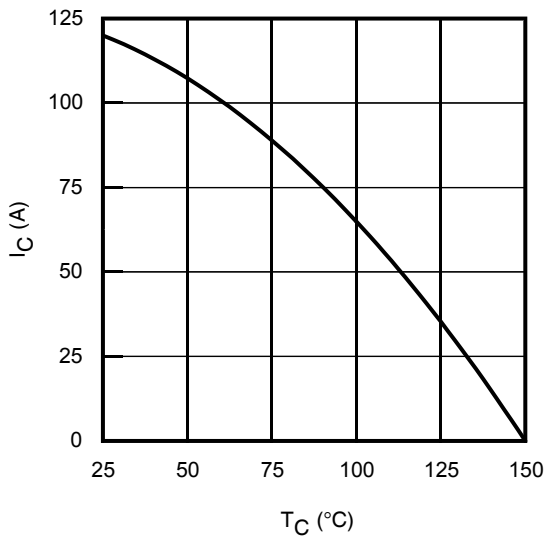
|              | Parameter                            | Min.        | Typ. | Max④ | Units   | Conditions                                                                                        |
|--------------|--------------------------------------|-------------|------|------|---------|---------------------------------------------------------------------------------------------------|
| $Q_g$        | Total Gate Charge (turn-on)          | —           | 290  | 435  | nC      | $I_C = 50A$<br>$V_{GE} = 15V$<br>$V_{CC} = 600V$                                                  |
| $Q_{ge}$     | Gate-to-Emitter Charge (turn-on)     | —           | 60   | 90   |         |                                                                                                   |
| $Q_{gc}$     | Gate-to-Collector Charge (turn-on)   | —           | 130  | 195  |         |                                                                                                   |
| $E_{on}$     | Turn-On Switching Loss               | —           | 4.8  | 5.7  | mJ      | $I_C = 50A, V_{CC} = 600V, V_{GE} = 15V$<br>$R_G = 5\Omega, T_J = 25^\circ\text{C}$               |
| $E_{off}$    | Turn-Off Switching Loss              | —           | 2.8  | 3.7  |         |                                                                                                   |
| $E_{total}$  | Total Switching Loss                 | —           | 7.6  | 9.4  |         |                                                                                                   |
| $t_{d(on)}$  | Turn-On delay time                   | —           | 110  | 130  | ns      | Energy losses include tail & diode reverse recovery ⑤⑥                                            |
| $t_r$        | Rise time                            | —           | 80   | 105  |         |                                                                                                   |
| $t_{d(off)}$ | Turn-Off delay time                  | —           | 490  | 520  |         |                                                                                                   |
| $t_f$        | Fall time                            | —           | 70   | 90   |         |                                                                                                   |
| $E_{on}$     | Turn-On Switching Loss               | —           | 6.8  | —    | mJ      | $I_C = 50A, V_{CC} = 600V, V_{GE} = 15V$<br>$R_G = 5\Omega, T_J = 150^\circ\text{C}$              |
| $E_{off}$    | Turn-Off Switching Loss              | —           | 4.7  | —    |         |                                                                                                   |
| $E_{total}$  | Total Switching Loss                 | —           | 11.5 | —    |         |                                                                                                   |
| $t_{d(on)}$  | Turn-On delay time                   | —           | 85   | —    | ns      | Energy losses include tail & diode reverse recovery ⑤⑥                                            |
| $t_r$        | Rise time                            | —           | 90   | —    |         |                                                                                                   |
| $t_{d(off)}$ | Turn-Off delay time                  | —           | 490  | —    |         |                                                                                                   |
| $t_f$        | Fall time                            | —           | 290  | —    |         |                                                                                                   |
| $C_{ies}$    | Input Capacitance                    | —           | 5700 | —    | pF      | $V_{GE} = 0V$<br>$V_{CC} = 30V$<br>$f = 1.0MHz$                                                   |
| $C_{oes}$    | Output Capacitance                   | —           | 290  | —    |         |                                                                                                   |
| $C_{res}$    | Reverse Transfer Capacitance         | —           | 150  | —    |         |                                                                                                   |
| RBSOA        | Reverse Bias Safe Operating Area     | FULL SQUARE |      |      |         | $T_J = 150^\circ\text{C}, I_C = 200A$<br>$V_{CC} = 960V, V_p \leq 1200V$<br>$V_{GE} = +20V$ to 0V |
| SCSOA        | Short Circuit Safe Operating Area    | 10          | —    | —    | $\mu s$ | $T_J = 150^\circ\text{C}, V_{CC} = 600V, V_p \leq 1200V$<br>$V_{GE} = +15V$ to 0V                 |
| $E_{rec}$    | Reverse Recovery Energy of the Diode | —           | 640  | —    | $\mu J$ | $T_J = 150^\circ\text{C}$                                                                         |
| $t_{rr}$     | Diode Reverse Recovery Time          | —           | 170  | —    | ns      | $V_{CC} = 600V, I_F = 16A$                                                                        |
| $I_{rr}$     | Peak Reverse Recovery Current        | —           | 25   | —    | A       | $V_{GE} = 15V, R_g = 5\Omega$                                                                     |

**Notes:**

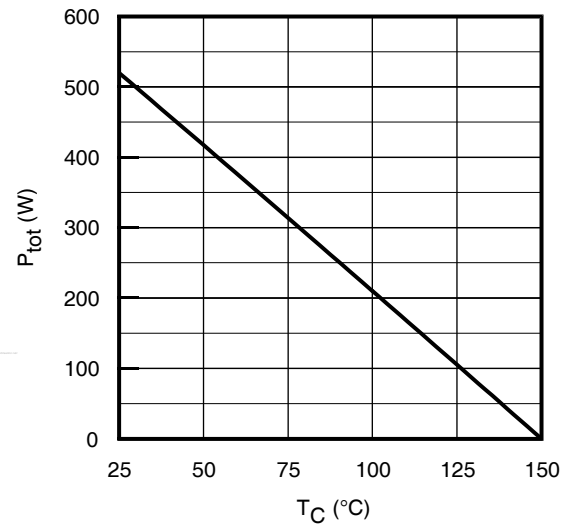
- ①  $V_{CC} = 80\% (V_{CES}), V_{GE} = 20V$
- ②  $R_\theta$  is measured at  $T_J$  of approximately  $90^\circ\text{C}$ .
- ③ Refer to AN-1086 for guidelines for measuring  $V_{(BR)CES}$  safely.
- ④ Maximum limits are based on statistical sample size characterization.
- ⑤ Pulse width limited by max. junction temperature.
- ⑥ Values influenced by parasitic L and C in measurement.



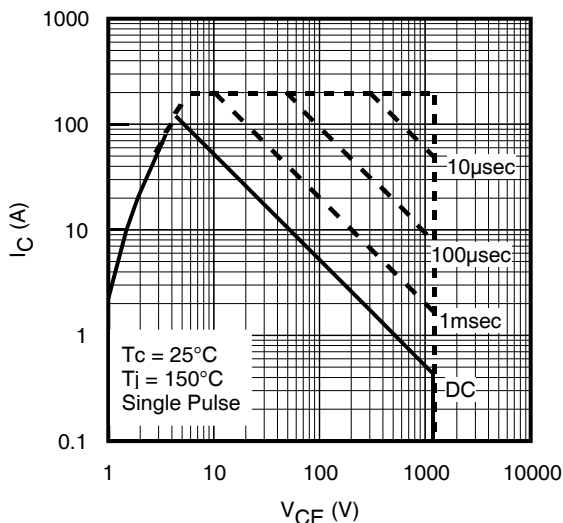
**Fig. 1 - Typical Load Current vs. Frequency**  
(Load Current =  $I_{\text{RMS}}$  of fundamental)



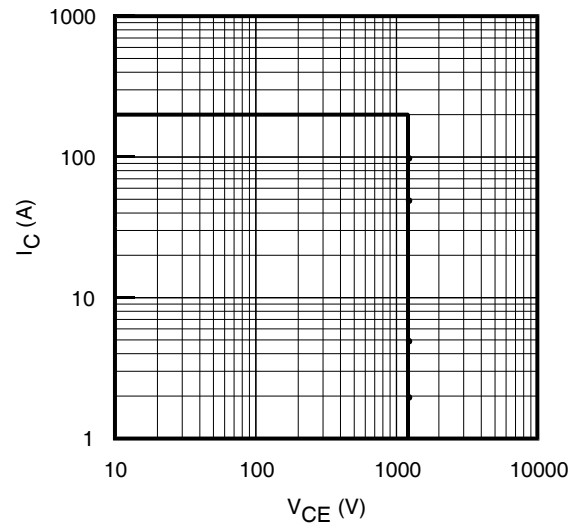
**Fig. 2 - Maximum DC Collector Current vs. Case Temperature**



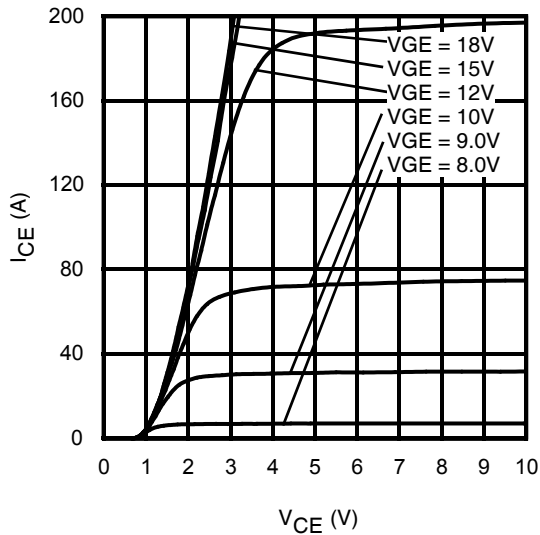
**Fig. 3 - Power Dissipation vs. Case Temperature**



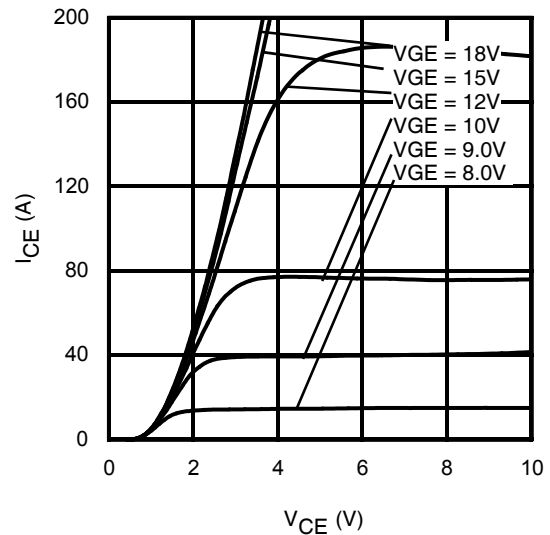
**Fig. 4 - Forward SOA**  
 $T_c = 25^{\circ}\text{C}$ ,  $T_j \leq 150^{\circ}\text{C}$ ,  $V_{\text{GE}} = 15\text{V}$



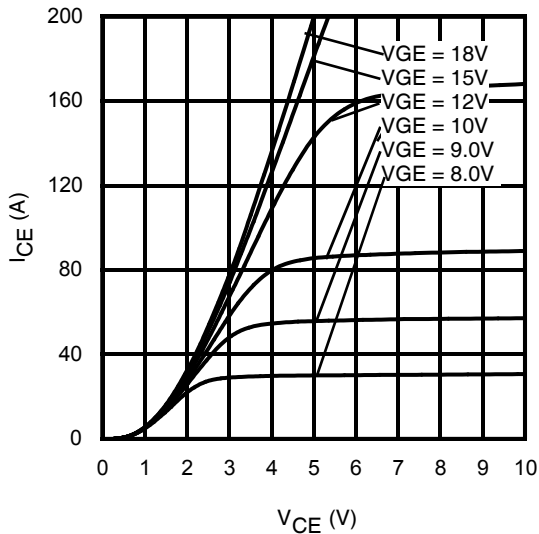
**Fig. 5- Reverse Bias SOA**  
 $T_j = 150^{\circ}\text{C}$ ;  $V_{\text{GE}} = 20\text{V}$



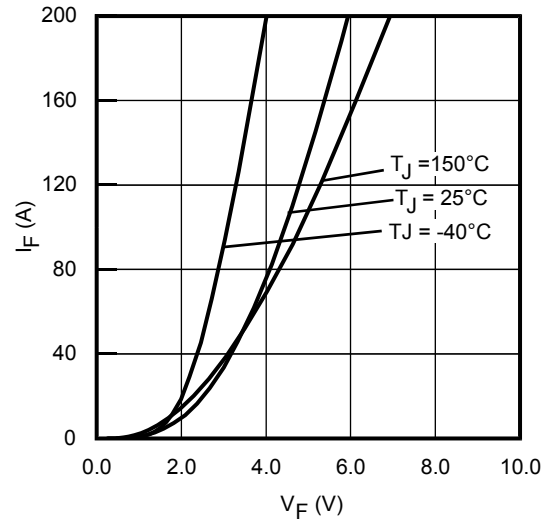
**Fig. 6** - Typ. IGBT Output Characteristics  
T<sub>J</sub> = -40°C; t<sub>p</sub> = 20μs



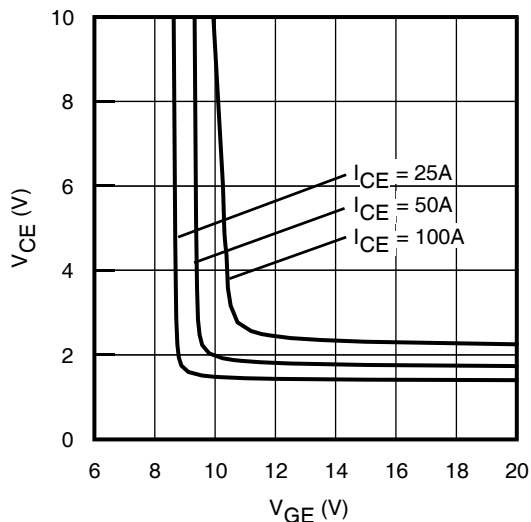
**Fig. 7** - Typ. IGBT Output Characteristics  
T<sub>J</sub> = 25°C; t<sub>p</sub> = 20μs



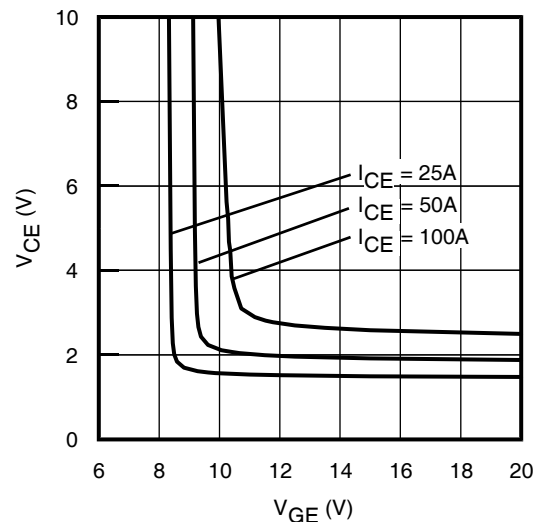
**Fig. 8** - Typ. IGBT Output Characteristics  
T<sub>J</sub> = 150°C; t<sub>p</sub> = 20μs



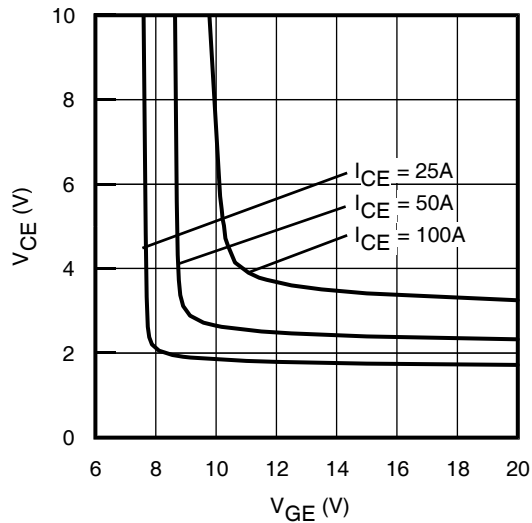
**Fig. 9** - Typ. Diode Forward Characteristics  
t<sub>p</sub> = 20μs



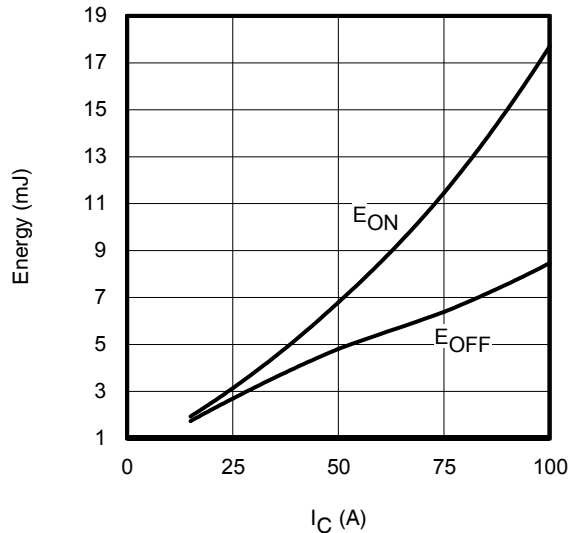
**Fig. 10** - Typical V<sub>CE</sub> vs. V<sub>GE</sub>  
T<sub>J</sub> = -40°C



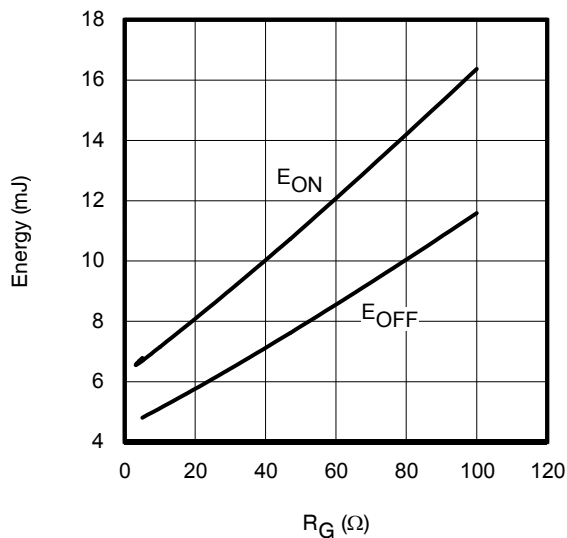
**Fig. 11** - Typical V<sub>CE</sub> vs. V<sub>GE</sub>  
T<sub>J</sub> = 25°C



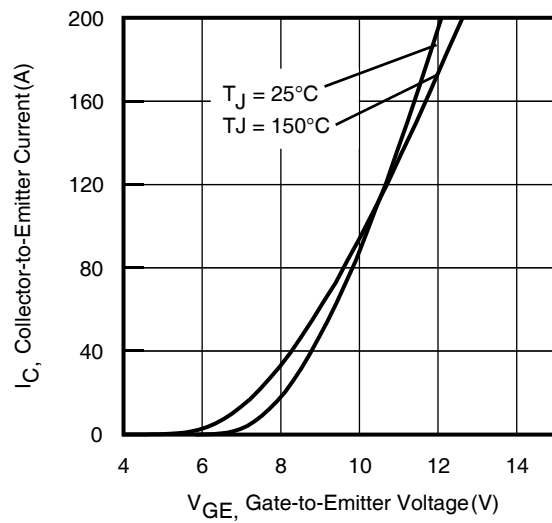
**Fig. 12** - Typical  $V_{CE}$  vs.  $V_{GE}$   
 $T_J = 150^\circ\text{C}$



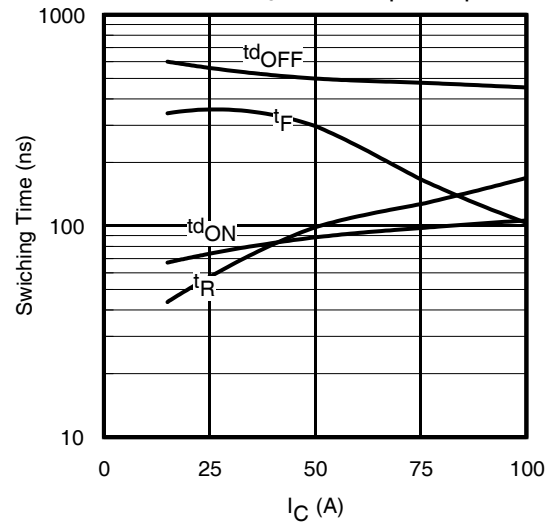
**Fig. 14** - Typ. Energy Loss vs.  $I_C$   
 $T_J = 150^\circ\text{C}$ ;  $V_{CE} = 600\text{V}$ ,  $R_G = 5\Omega$ ;  $V_{GE} = 15\text{V}$



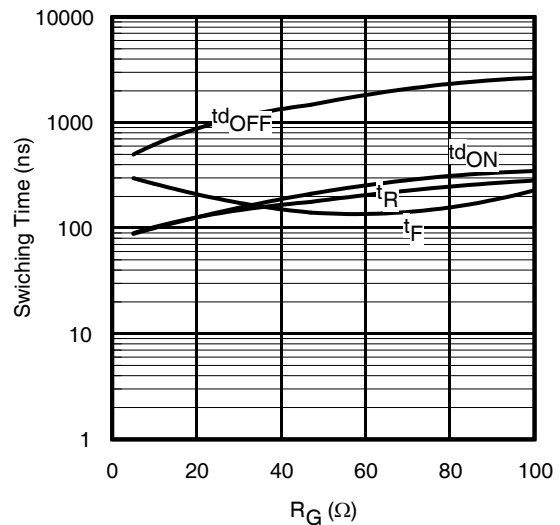
**Fig. 16** - Typ. Energy Loss vs.  $R_G$   
 $T_J = 150^\circ\text{C}$ ;  $V_{CE} = 600\text{V}$ ,  $I_{CE} = 50\text{A}$ ;  $V_{GE} = 15\text{V}$



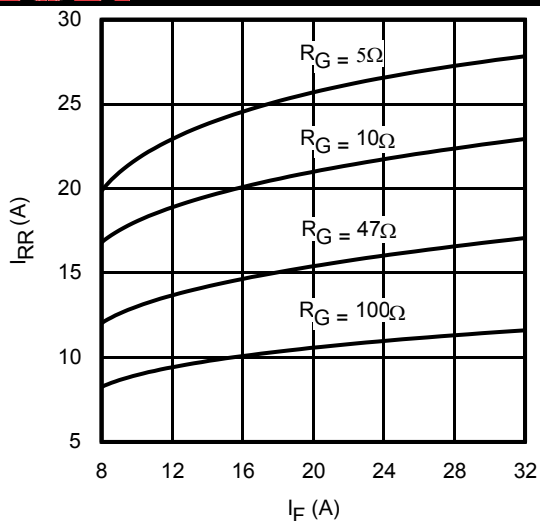
**Fig. 13** - Typ. Transfer Characteristics  
 $V_{CE} = 50\text{V}$ ;  $t_p = 20\mu\text{s}$



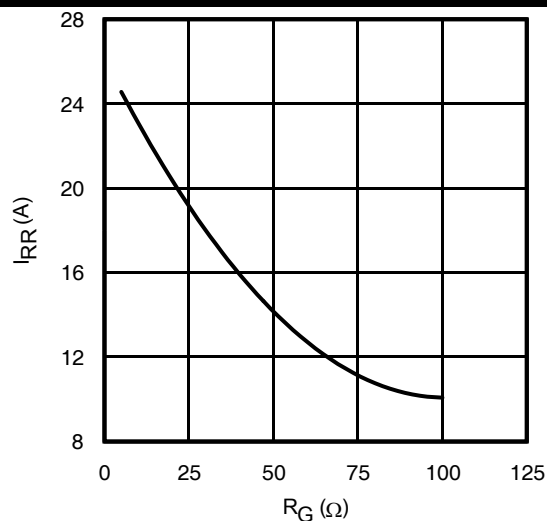
**Fig. 15** - Typ. Switching Time vs.  $I_C$   
 $T_J = 150^\circ\text{C}$ ;  $V_{CE} = 600\text{V}$ ,  $R_G = 5\Omega$ ;  $V_{GE} = 15\text{V}$



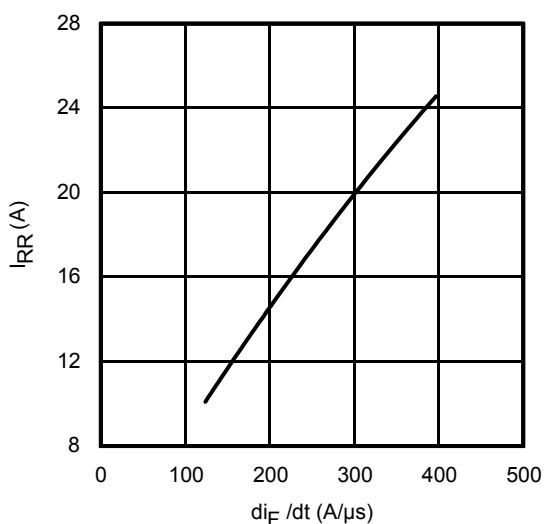
**Fig. 17** - Typ. Switching Time vs.  $R_G$   
 $T_J = 150^\circ\text{C}$ ;  $V_{CE} = 600\text{V}$ ,  $I_{CE} = 50\text{A}$ ;  $V_{GE} = 15\text{V}$



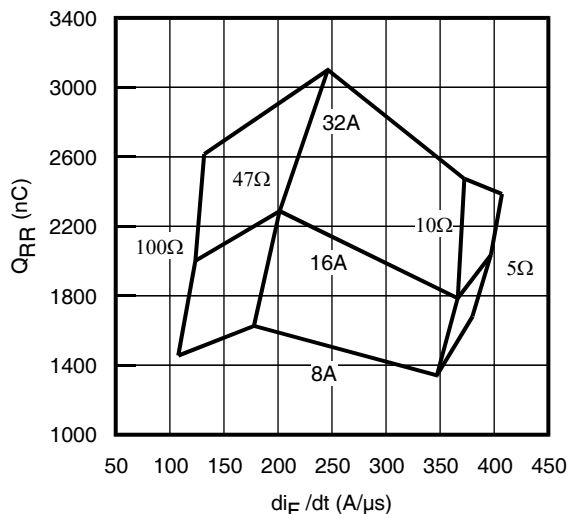
**Fig. 18** - Typ. Diode  $I_{RR}$  vs.  $I_F$   
 $T_J = 150^\circ\text{C}$



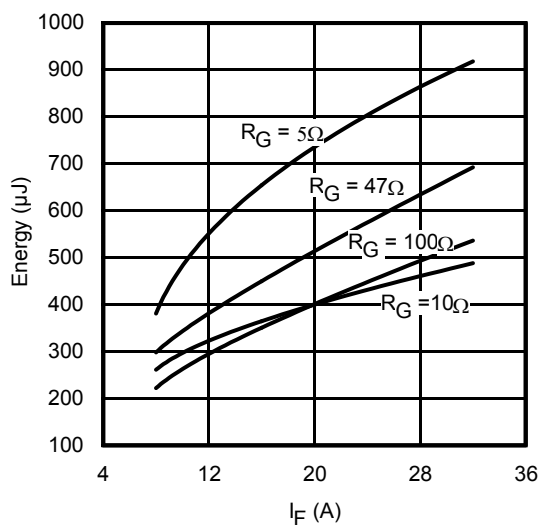
**Fig. 19** - Typ. Diode  $I_{RR}$  vs.  $R_G$   
 $T_J = 150^\circ\text{C}$



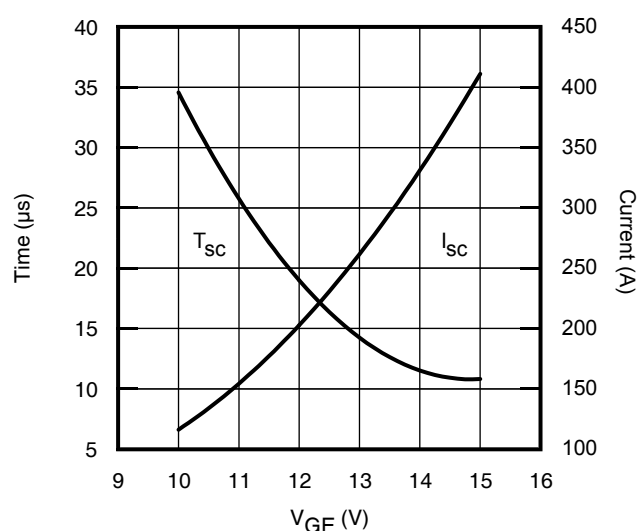
**Fig. 20** - Typ. Diode  $I_{RR}$  vs.  $di_F/dt$   
 $V_{CC} = 600\text{V}$ ;  $V_{GE} = 15\text{V}$ ;  $I_F = 16\text{A}$ ;  $T_J = 150^\circ\text{C}$



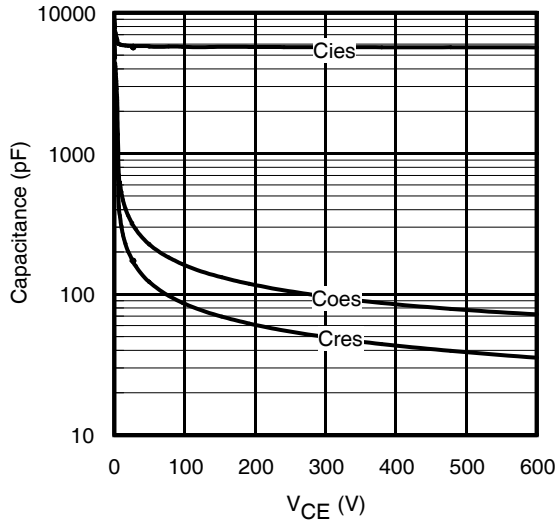
**Fig. 21** - Typ. Diode  $Q_{RR}$  vs.  $di_F/dt$   
 $V_{CC} = 600\text{V}$ ;  $V_{GE} = 15\text{V}$ ;  $T_J = 150^\circ\text{C}$



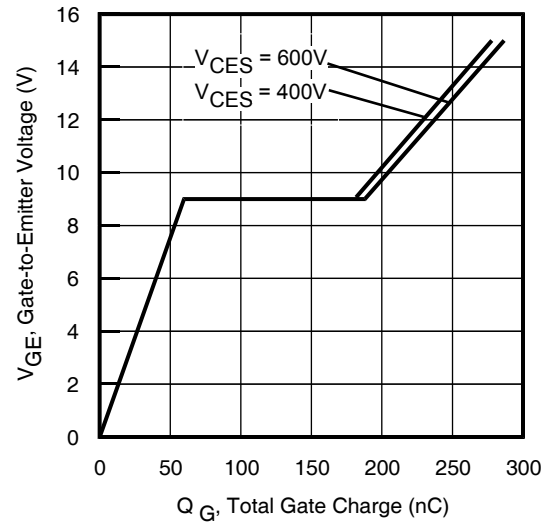
**Fig. 22** - Typ. Diode  $E_{RR}$  vs.  $I_F$   
 $T_J = 150^\circ\text{C}$



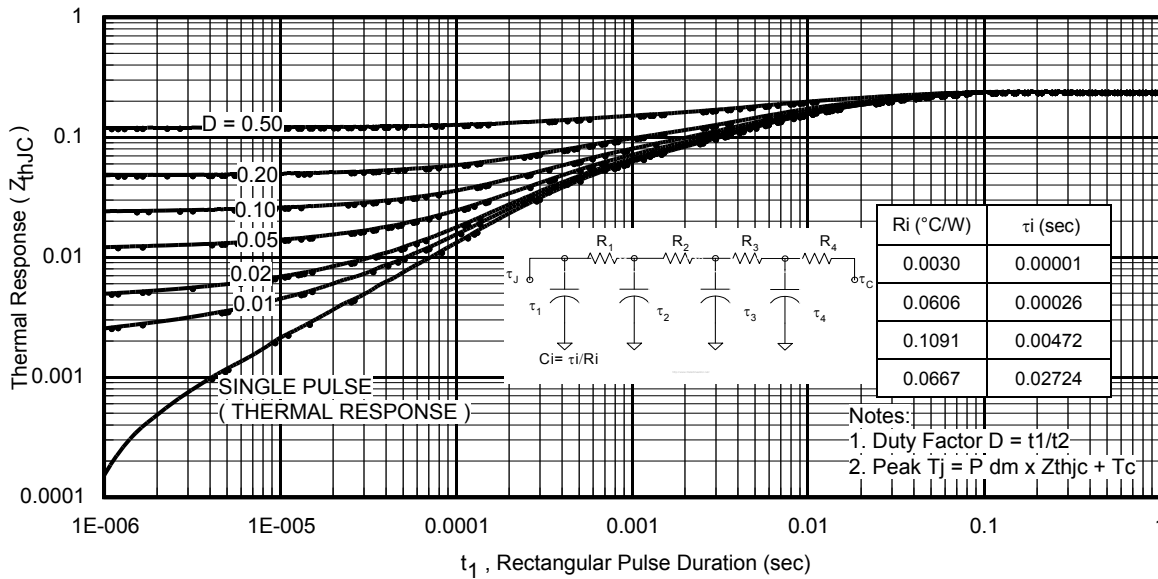
**Fig. 23** -  $V_{CE}$  vs. Short Circuit Time  
 $V_{CC} = 600\text{V}$ ;  $T_C = 150^\circ\text{C}$



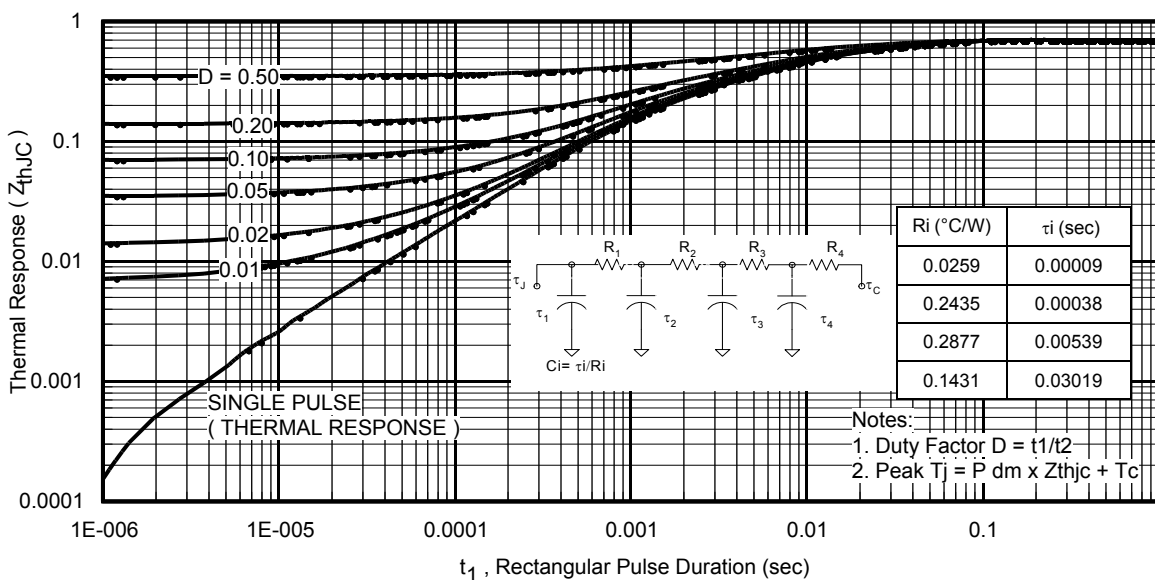
**Fig. 24** - Typ. Capacitance vs.  $V_{CE}$   
 $V_{GE} = 0V$ ;  $f = 1MHz$



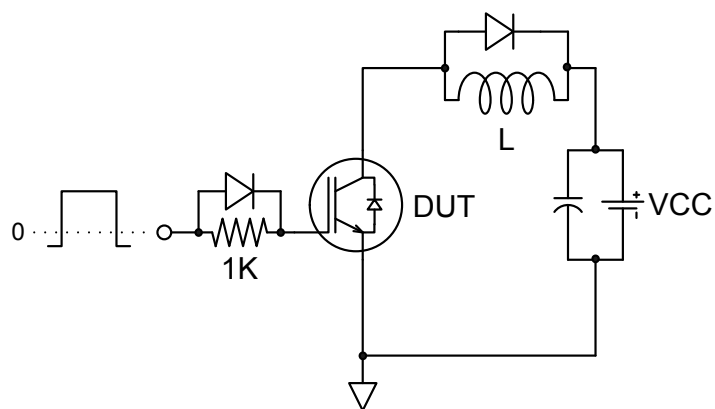
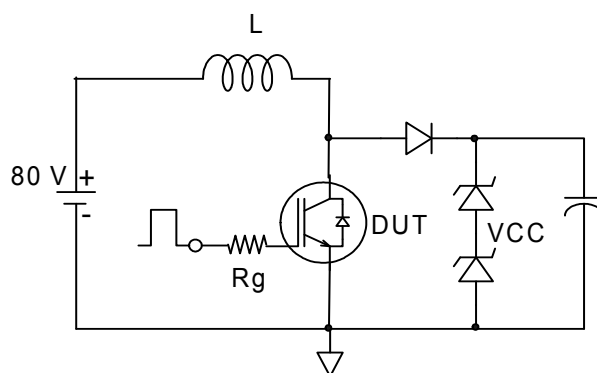
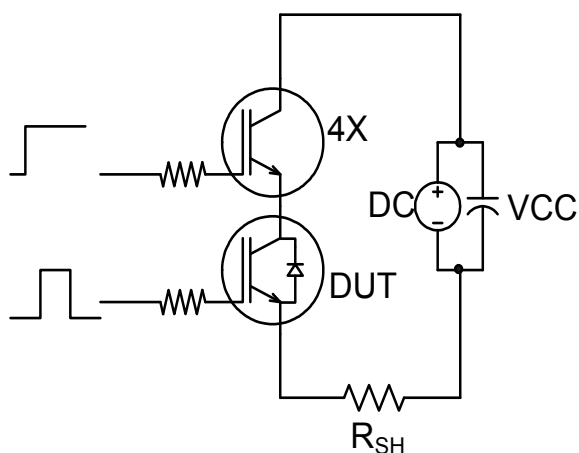
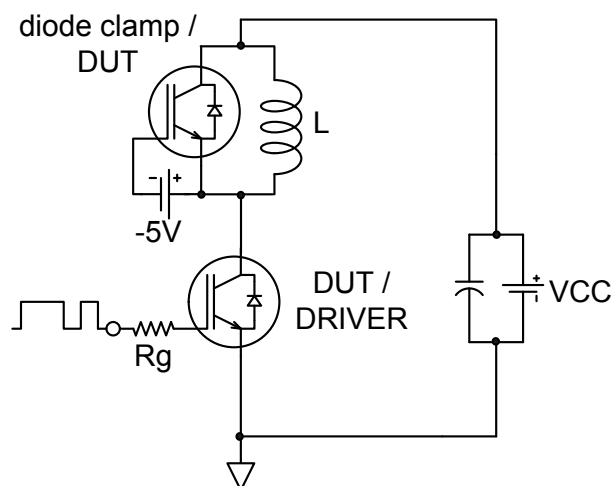
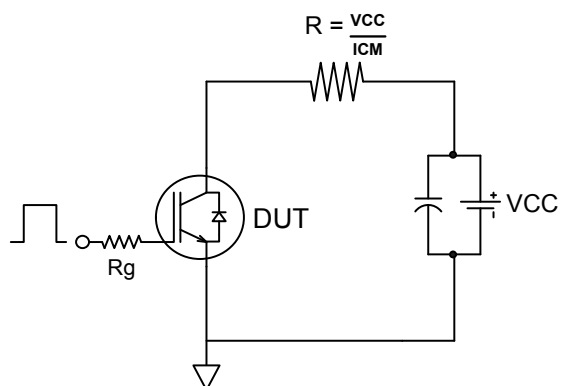
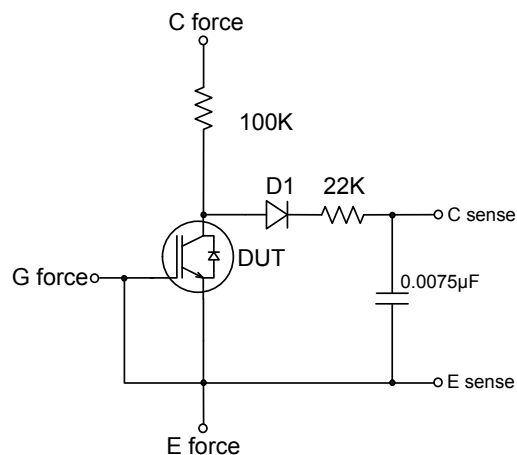
**Fig. 25** - Typical Gate Charge vs.  $V_{GE}$   
 $I_{CE} = 50A$



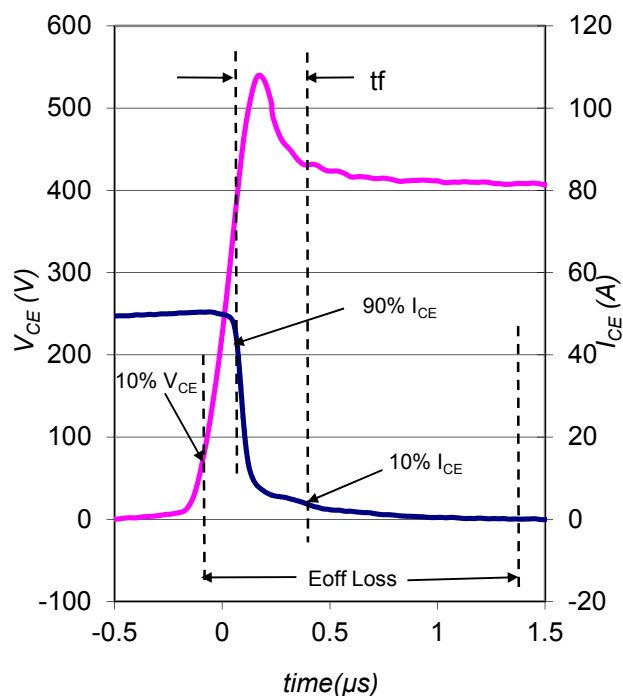
**Fig. 26** Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)



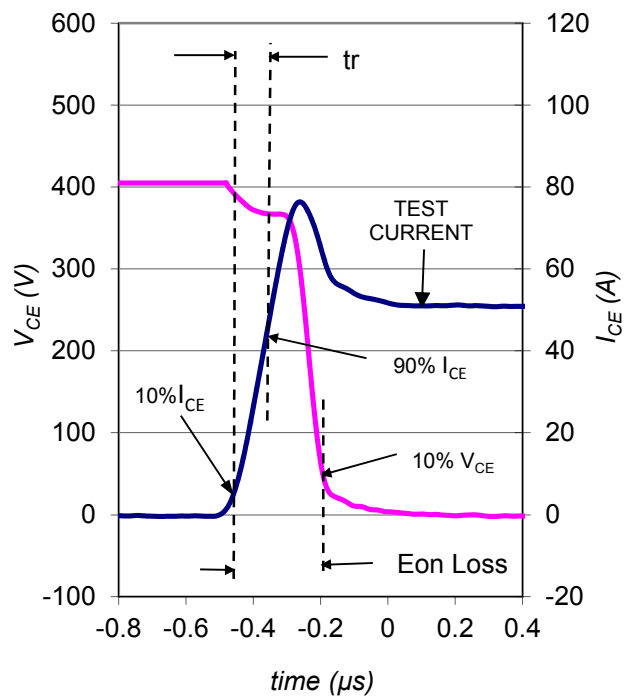
**Fig. 27** Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)


**Fig.C.T.1 - Gate Charge Circuit (turn-off)**

**Fig.C.T.2 - RBSOA Circuit**

**Fig.C.T.3 - S.C. SOA Circuit**

**Fig.C.T.4 - Switching Loss Circuit**

**Fig.C.T.5 - Resistive Load Circuit**

**Fig.C.T.6 - BVCES Filter Circuit**

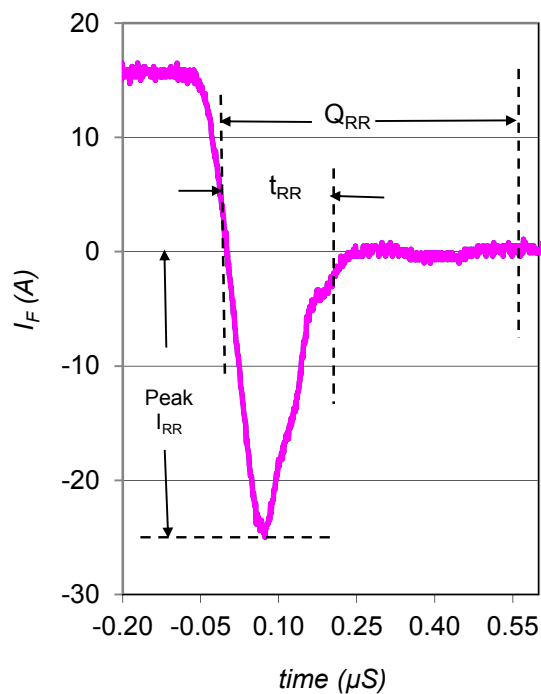




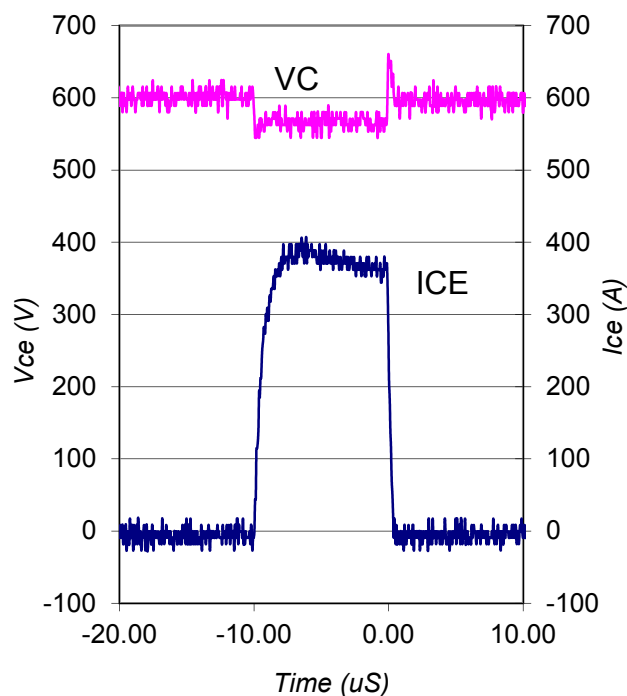
**Fig. WF1** - Typ. Turn-off Loss Waveform  
@  $T_J = 150^{\circ}\text{C}$  using Fig. CT.4



**Fig. WF2** - Typ. Turn-on Loss Waveform  
@  $T_J = 150^{\circ}\text{C}$  using Fig. CT.4



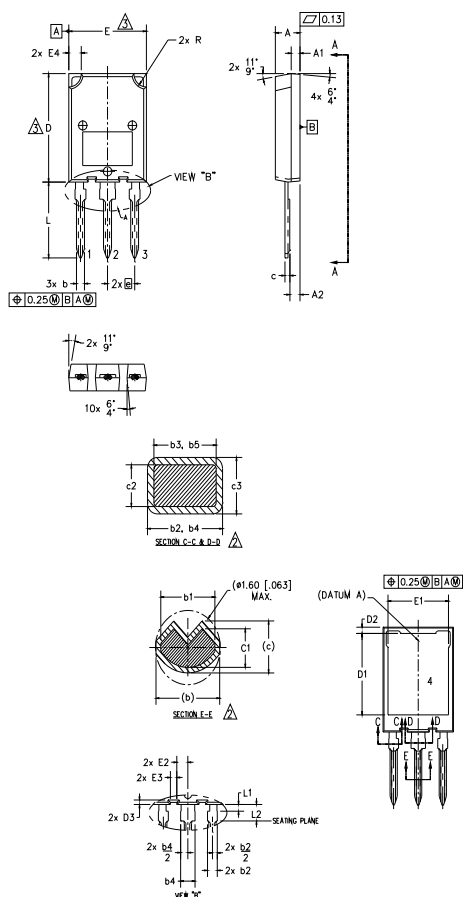
**Fig. WF3** - Typ. Diode Recovery Waveform  
@  $T_J = 150^{\circ}\text{C}$  using Fig. CT.4



**Fig. WF4** - Typ. S.C. Waveform  
@  $T_J = 150^{\circ}\text{C}$  using Fig. CT.3

## Super -247(TO-274AA) Package Outline

Dimensions are shown in millimeters (inches)



### NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M-1994
2. DIMENSIONS b1, b3, b5, c1 & c3 APPLY TO BASE METAL ONLY.
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTER EXTREMES OF THE PLASTIC BODY.
4. ALL DIMENSIONS SHOWN IN MILLIMETERS.
5. CONTROLLING DIMENSION: MILLIMETER.
6. OUTLINE CONFORMS TO JEDEC OUTLINE TO-274AA

| SYMBOL | DIMENSIONS  |       |          |      | NOTES |
|--------|-------------|-------|----------|------|-------|
|        | MILLIMETERS |       | INCHES   |      |       |
|        | MIN.        | MAX.  | MIN.     | MAX. |       |
| A      | 4.50        | 5.50  | .177     | .217 | 2     |
| A1     | 1.45        | 2.15  | .057     | .085 |       |
| A2     | 1.65        | 2.35  | .065     | .093 |       |
| b      | 1.45        | 1.60  | .054     | .063 |       |
| b1     | 1.40        | 1.50  | .055     | .059 |       |
| b2     | 2.00        | 2.40  | .079     | .094 | 2     |
| b3     | 1.95        | 2.35  | .077     | .093 |       |
| b4     | 3.00        | 3.15  | .118     | .124 |       |
| b5     | 2.95        | 3.35  | .116     | .132 | 2     |
| c      | 1.10        | 1.30  | .043     | .051 | 2     |
| c1     | 0.90        | 1.10  | .035     | .043 |       |
| c2     | 0.65        | 0.85  | .026     | .033 |       |
| c3     | 0.50        | 0.70  | .020     | .028 | 2     |
| D      | 19.80       | 20.80 | .780     | .819 | 3     |
| D1     | 15.50       | 16.10 | .610     | .634 |       |
| D2     | 0.70        | 1.30  | .028     | .051 |       |
| D3     | 0.75        | 1.25  | .030     | .049 | 3     |
| E      | 15.10       | 16.10 | .594     | .634 |       |
| E1     | 13.30       | 13.90 | .524     | .547 |       |
| E2     | 2.25        | 2.70  | .089     | .109 |       |
| E3     | 1.20        | 1.70  | .047     | .067 |       |
| E4     | 2.00        | 3.00  | .079     | .118 |       |
| e      | 5.45 BSC    |       | .215 BSC |      |       |
| L      | 13.80       | 14.80 | .535     | .583 |       |
| L1     | 1.00        | 1.60  | .039     | .063 |       |
| L2     | 3.85        | 4.25  | .152     | .167 |       |
| R      | 2.00        | 3.00  | .079     | .118 |       |

### LEAD ASSIGNMENTS

#### MOSFET

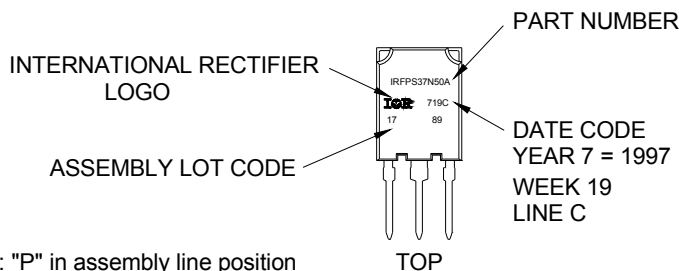
1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

#### IGBT

1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

## Super -247 (TO-274AA) Part Marking Information

EXAMPLE: THIS IS AN IRFPS37N50A WITH  
ASSEMBLY LOT CODE 1789  
ASSEMBLED ON WW 19, 1997  
IN THE ASSEMBLY LINE "C"



Note: "P" in assembly line position indicates "Lead-Free"

Super -247 package is not recommended for Surface Mount Application.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

**Qualification Information<sup>†</sup>**

|                                   |                                                 |     |
|-----------------------------------|-------------------------------------------------|-----|
| <b>Qualification Level</b>        | Industrial<br>(per JEDEC JESD47F) <sup>††</sup> |     |
| <b>Moisture Sensitivity Level</b> | Super-247                                       | N/A |
| <b>RoHS Compliant</b>             | Yes                                             |     |

<sup>†</sup> Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/product-info/reliability/>

<sup>††</sup> Applicable version of JEDEC standard at the time of product release.

Data and specifications subject to change without notice.

International  
 Rectifier

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